

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HIROSHI KITAGAWA	08/08/2018
KOHEI KUSADA	08/09/2018
DONGSHUANG WU	08/21/2018
RECEIVING PARTY DATA	
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City:	KYOTO-SHI, KYOTO
State/Country:	JAPAN
Postal Code:	606-8501
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16081916
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NAME OF SUBMITTER:	JOHN KILYK, JR.
SIGNATURE:	/John Kilyk, Jr./
DATE SIGNED:	09/02/2018
Total Attachments: 3	
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ASSIGNMENT

WHEREAS, I/WE

(1) **Hiroshi KITAGAWA**, c/o Kyoto University, 36-1, Yoshida-honmachi, Sakyo-ku, Kyoto-shi, Kyoto 6068501, Japan;

(2) **Kohei KUSADA**, c/o Kyoto University, 36-1, Yoshida-honmachi, Sakyo-ku, Kyoto-shi, Kyoto 6068501, Japan;

(3) **Dongshuang WU**, c/o Kyoto University, 36-1, Yoshida-honmachi, Sakyo-ku, Kyoto-shi, Kyoto 6068501, Japan;

hereinafter referred to as Assignor, have invented a certain invention entitled:

MULTICOMPONENT SOLID SOLUTION MICROPARTICLES AND METHOD FOR PRODUCING SAME, AND CATALYST

for which invention an application (provisional or non-provisional) for a U.S. patent was filed on September 2, 2018, under U.S. Application No. 16/081,916, and

WHEREAS, **Kyoto University** of 36-1, Yoshida-honmachi, Sakyo-ku, Kyoto-shi, Kyoto 6068501, Japan, hereinafter referred to as Assignee, is desirous of acquiring the entire right, title, and interest in, to, and under the invention described in the patent application, including the entire priority right derived from the application,

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged,

Assignor assigns and transfers to Assignee and Assignee's legal representatives, successors, and assigns the entire right, title, and interest in, to, and under the invention, the referenced patent application, other such applications (e.g., provisional applications, non-provisional applications, continuations, continuations-in-part, divisionals, reissues, reexaminations, national and regional phase applications, petty patent applications, and utility model applications) that may be filed in the U.S. and/or any country foreign to the U.S. on the invention, the patents that may issue thereon, and the patents as may be modified as the result of applicable procedures (e.g., supplemental examinations, ex parte reexaminations, inter partes reexaminations, inter partes reviews, post-grant reviews, and oppositions),

Assignor conveys to the Assignee the right to make applications in Assignee's own behalf for protection of the invention in the U.S. and countries foreign to the U.S. and to claim priority to the referenced patent application and other such applications that may be filed in the U.S. or any country foreign to the U.S. on the invention under the Patent Cooperation Treaty, the Paris Convention, and any other international arrangements,

Assignor will not execute any writing or do any act conflicting with the terms of this assignment,

Assignor will at any time upon request, without further or additional consideration, but at the expense of the Assignee, execute such additional assignments and other writings and do such additional acts as the Assignee may deem necessary or desirable to pursue the patent applications identified herein, including, but not limited to, rendering all necessary assistance in making applications for and obtaining patents that may issue thereon in the U.S. and any countries foreign to the U.S. on the invention, and in enforcing any rights accruing as a result of such applications or patents, by, for example, executing statements and other affidavits,

Assignor and Assignee agree the terms of this assignment shall bind, and inure to the benefit of, the legal representatives, successors, and assigns of all parties hereto.

Assignor authorizes Assignee to insert in this assignment the number and filing date of the application if the number and filing date of the application are not recited herein at the time of execution of this assignment by any or all of the parties hereto,

Assignor and Assignee agree that U.S. law governs this assignment, and

Assignee acknowledges and accepts this assignment.

IN WITNESS WHEREOF, Assignor has hereunder set his/her hand on the date shown below:

Date August, 8, 2018

Hiroshi Kitagawa
Assignor: Hiroshi KITAGAWA

Date August, 8, 2018

Jan-ichi Sakiyama
Witness:

Date August 8, 2018

Hanako Minami
Witness:

Date August 9, 2018

Kohei Kusada
Assignor: Kohei KUSADA

Date August 9, 2018

Jan-ichi Sakiyama
Witness:

Date August 9, 2018

Hanako Minami
Witness:

Date August 21, 2018

Dongshuang Wu
Assignor: Dongshuang WU

Date August 21, 2018

Jun-ichi Sakiyama
Witness:

Date AUGUST 21, 2018

Hanako Minami
Witness:

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